MSAP

半加成法工艺

对于细线路而言，MSAP是一种经济高效的工艺来帮助达成高度自动化，高产量和精益生产。
MacDermid Alpha提供一个组合方案涵盖了每个工艺。请询问MacDermid Alpha 代表介绍 MSAP

减铜
CircuEtch 100

雷射钻孔前处理
MultiBond 500

雷射钻孔后处理
CoreClean

初级金属化
Systek Desmear
Shadow LE, Eclipse LE
M-Copper Series

雷射钻孔后处理
MultiPrep 200

干膜显影剂
Developer 45 Plus

图形电镀与填孔电镀
MacuSpec AVF
MacuSpec VF-TH

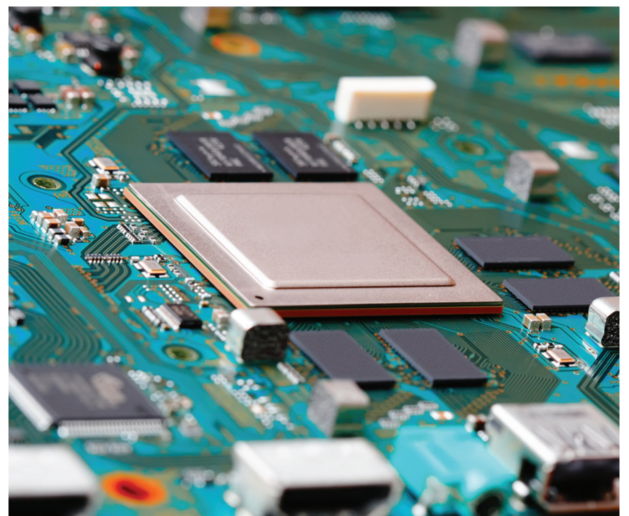
剥干膜
UltraStrip LDI

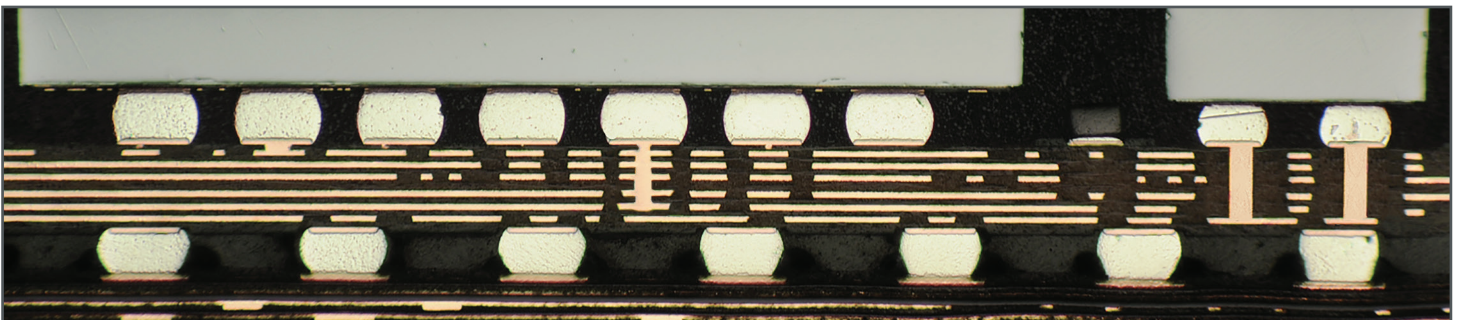
差异性蚀刻
CircuEtch 200

内层压合前处理
MultiBond 500

防焊绿油前处理
MultiPrep 200

最终表面处理
ENTEK PLUS HT
Affinity ENIG/ENEPIG





macdermidalpha.com
October, 2019

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